

Deca Technologies Ships 100-Millionth Wafer-Level Packaged Component

Fully Automated Manufacturing Technology Drives Growth for WLP Startup

TEMPE, Ariz., April 16, 2014 – Deca Technologies, an electronic interconnect solutions provider to the semiconductor industry, today announced that it has shipped its 100-millionth component. The company attributes this milestone to strong demand from portable electronics manufacturers for wafer-level chip scale packages (WLCSP) manufactured using Deca's unique, integrated Autoline production platform, which is designed to achieve faster time-to-market at lower cost.

Leveraging advanced Autoline volume production technologies from SunPower Corp. (NASDAQ:SPWR), a leading solar technology and energy services provider, Deca quickly achieved this milestone by addressing cycle time and capital cost challenges that semiconductor device manufacturers have struggled with using the conventional approach to WLCSP manufacturing.

Demand for WLCSP is being driven by manufacturers of wireless connectivity, audio and power management components for the handset and wearable electronics markets. Demand fluctuations in these markets can lead to challenges in managing inventories. Customers have found that Deca's unique approach helps them better manage their inventories and reduce their working capital.

"Congratulations to the Deca team on achieving this significant milestone," said Brent Wilson, senior vice president of the Global Supply Chain Organization at ON Semiconductor. "Deca's innovative technologies and focus on customer service have made the company a valuable part of our supply chain. We look forward to continued shared success in the future."

"Reaching 100 million units is an important milestone for Deca because it validates our unique approach to WLCSP manufacturing," said Chris Seams, CEO of Deca Technologies. "Based on the demand forecasted by our customers, we anticipate passing the half-billion mark in unit shipments this year."

“As a customer of Deca Tech, Cypress has used the fast New Product Introduction capability of Deca to streamline its back-end process and achieve cycle times of fewer than three days for full turnkey wafer-level packaging, test and singulation,” said T.J. Rodgers, president and CEO of Cypress Semiconductor Corp. “We are even more pleased with Deca as our subsidiary,” Rodgers continued. “The company’s quick ramp to the 100-million-unit milestone is proof of the value proposition that we envisioned when we invested in this market.”

About Deca Technologies

Founded in 2009 and launched in November 2011, Deca Technologies is an electronic interconnect solutions provider offering wafer-level packaging (WLP) services to the semiconductor industry. Headquartered in Tempe, Ariz., and with global capabilities, Deca is a majority-owned and fully independent subsidiary of Cypress Semiconductor Corp. (NASDAQ: CY). Deca’s mission is to deliver an exceptional customer experience through its proprietary and transformative interconnect technology. Integrating its solar and semiconductor background, Deca leverages unique equipment, processes and operational methods to break down traditional barriers in the continued adoption and growth of next-generation wafer-level electronic interconnect. For more information, please visit <http://www.decatechnologies.com>.

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